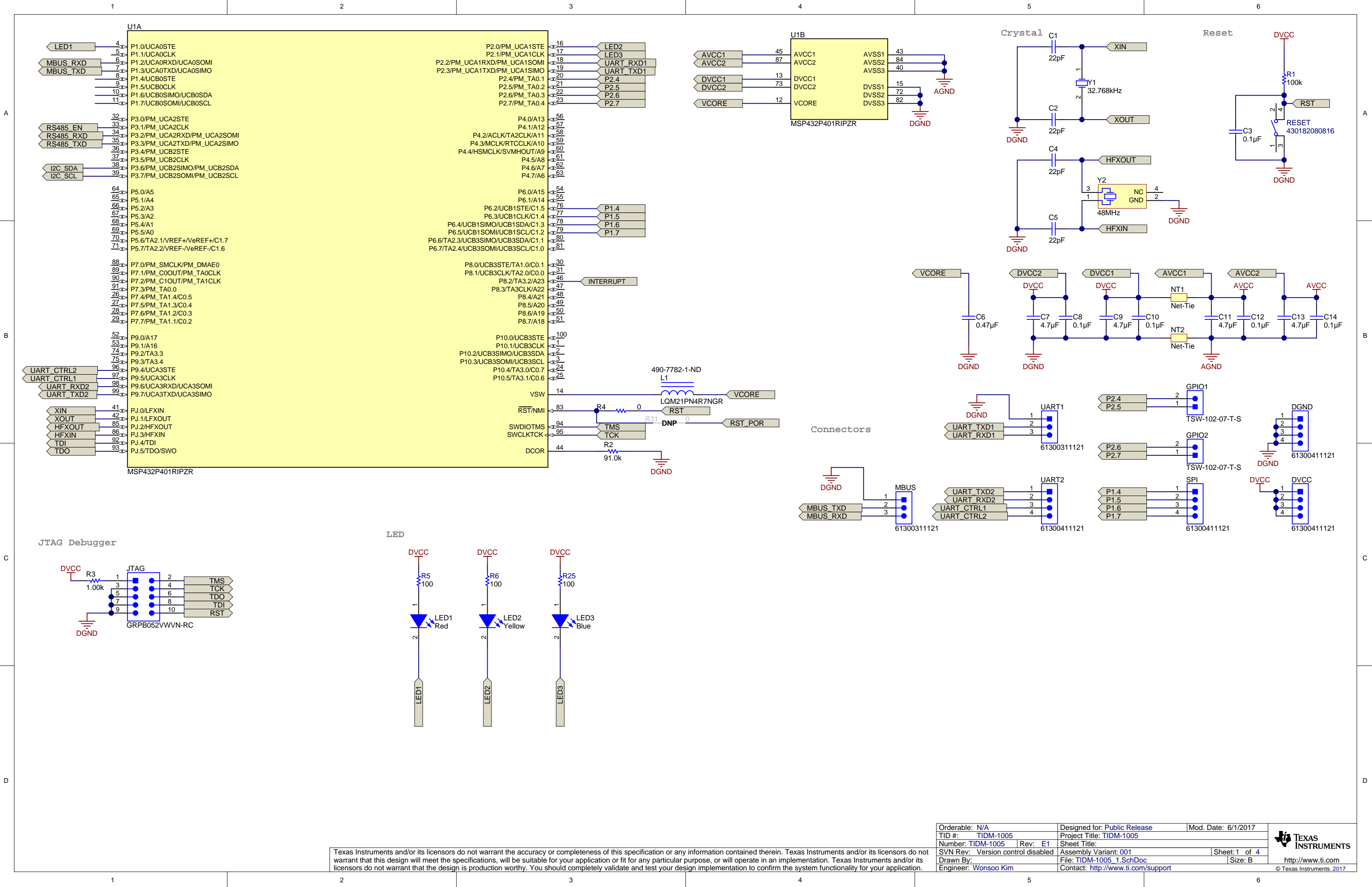


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TID #: TIDM-1005	Project Title: TIDM-1005	
Number: TIDM-1005	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 0 of 4
Drawn By:	File: TIDM-1005_CoverSheet.SchDoc	Size: B
Engineer: Wonsoo Kim	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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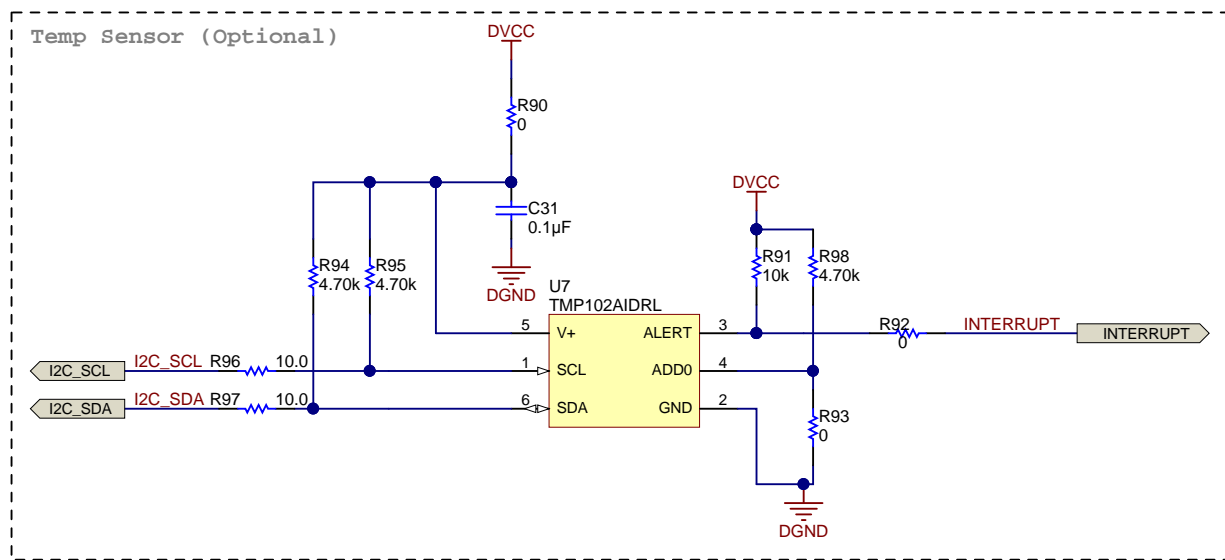
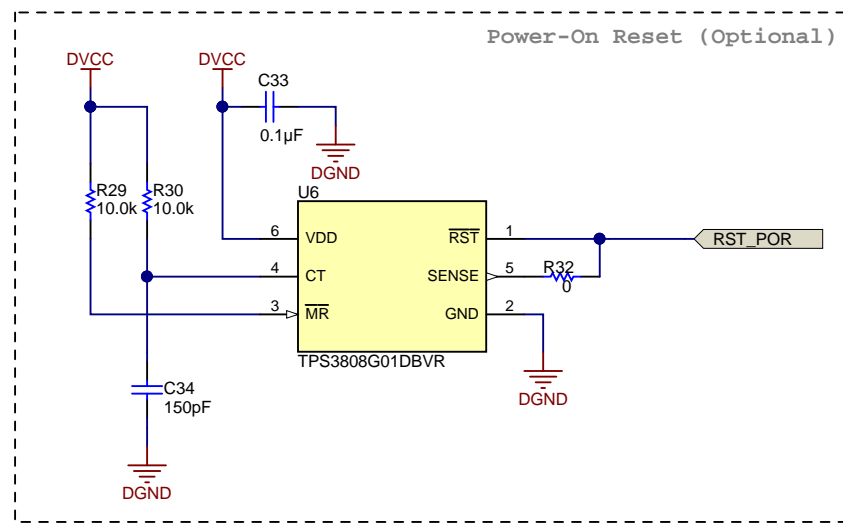




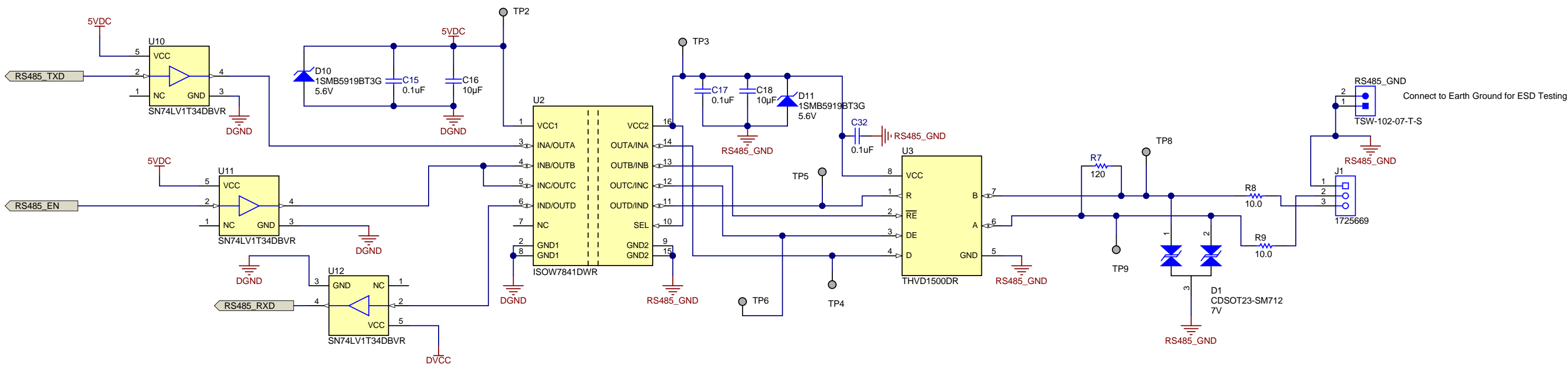
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TID #: TIDM-1005	Project Title: TIDM-1005	
Number: TIDM-1005	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 4
Drawn By:	File: TIDM-1005_1.SchDoc	Size: B
Engineer: Wonsoo Kim	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	





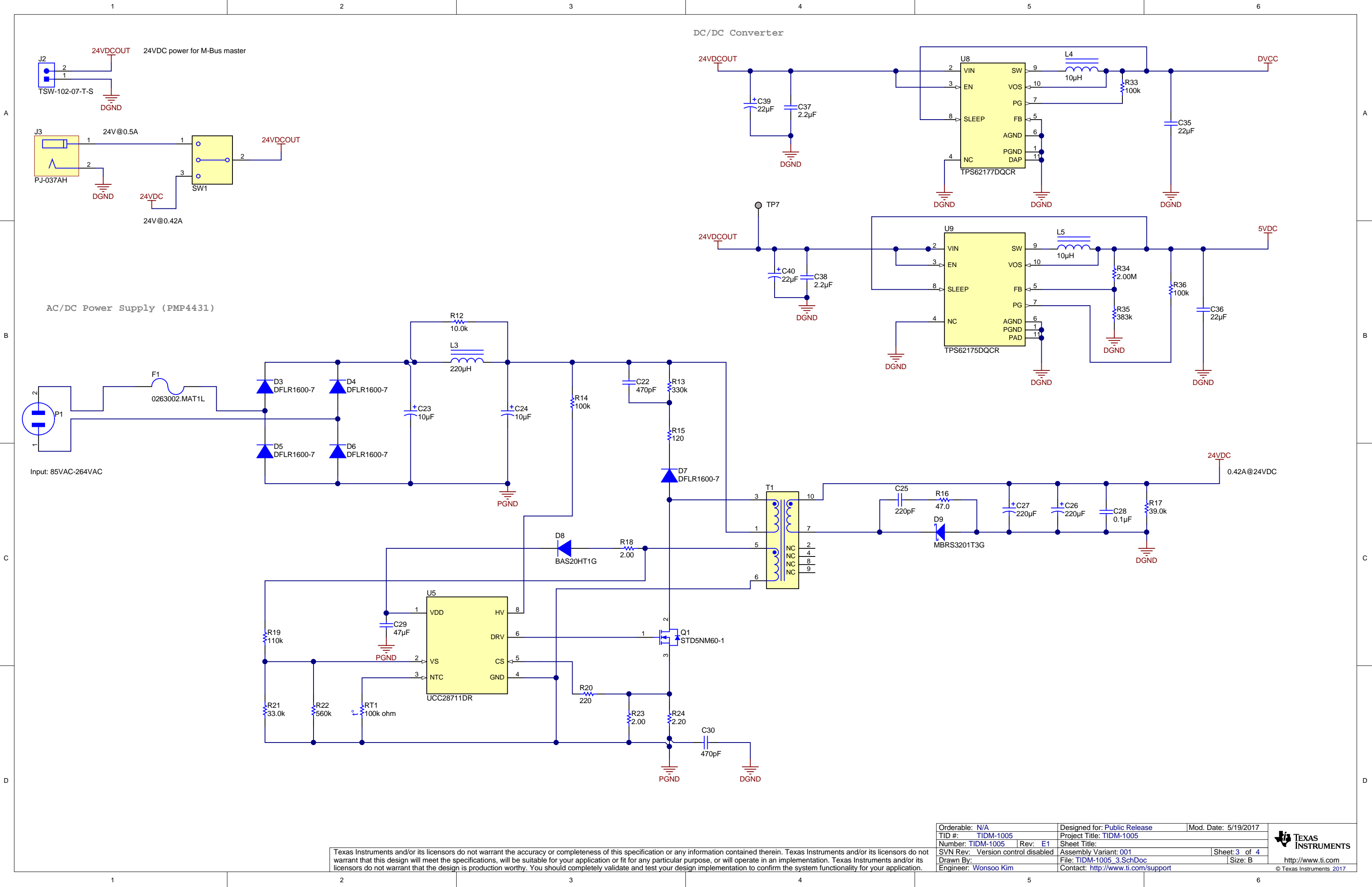
### RS-485 Transceiver



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TID #: TIDM-1005	Project Title: TIDM-1005	
Number: TIDM-1005	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 4
Drawn By:	File: TIDM-1005_2.SchDoc	Size: B
Engineer: Wonsoo Kim	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

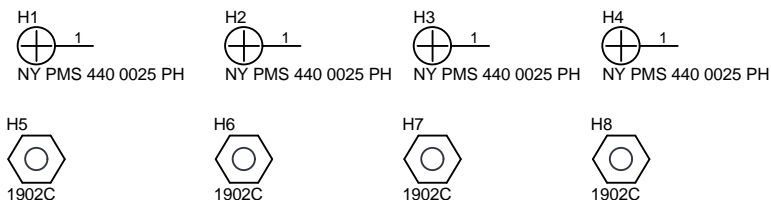




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TID #: TIDM-1005	Project Title: TIDM-1005	
Number: TIDM-1005	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 4
Drawn By:	File: TIDM-1005_3.SchDoc	Size: B
Engineer: Wonsoo Kim	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	





PCB Number: TIDM-1005  
PCB Rev: E1

PCB  
LOGO  
Pb-Free Symbol



Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 5/11/2017
TID #: TIDM-1005	Project Title: TIDM-1005	
Number: TIDM-1005	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 4
Drawn By:	File: TIDM-1005-EVM_Hardware.SchDoc	Size: B
Engineer: Wonsoo Kim	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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